

tec-speed 4.0 - VT-462(L) PP

UL Approval: E214381 Preliminary B1.0

Low Dk / Low Loss No & Low Flow Prepreg

General Information

- > High Tg
- > FR4.0
- > Low Dk & Low Loss
- > Excellent Thermal Reliability
- > Lead Free Process Compatible
- > Ease of Manufacturing

Application

All flex-rigid applications with high BPS data rates, High speed flex-rigid connectors, High frequency & high Speed, satellite communication, navigation, GPS, etc

Availability

Type	Glass Fabric	Resin Content	Flow Range		Pressed Thickness	
			mil	mm	mil/ply	mm/ply
1067NF	1067	65%	5~50	0.125~1.25	2.2	0.056
1067LF	1067	68%	60~120	1.5~3.0	2.4	0.060
1078NF	1078	60%	5~50	0.125~1.25	2.8	0.071
1080LF	1080	65%	60~120	1.5~3.0	3.3	0.084

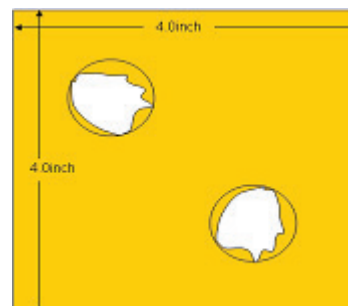
Remark:

"NF" ---- No Flow PP

"LF" ---- Low Flow PP

Right picture shows Flow-in test method:→

1. Press Temperature ---- 171 °C
2. 3 plys per pressing
3. Press Pressure ---- 200psi Built on IPC-TM650, 2.3.17.2



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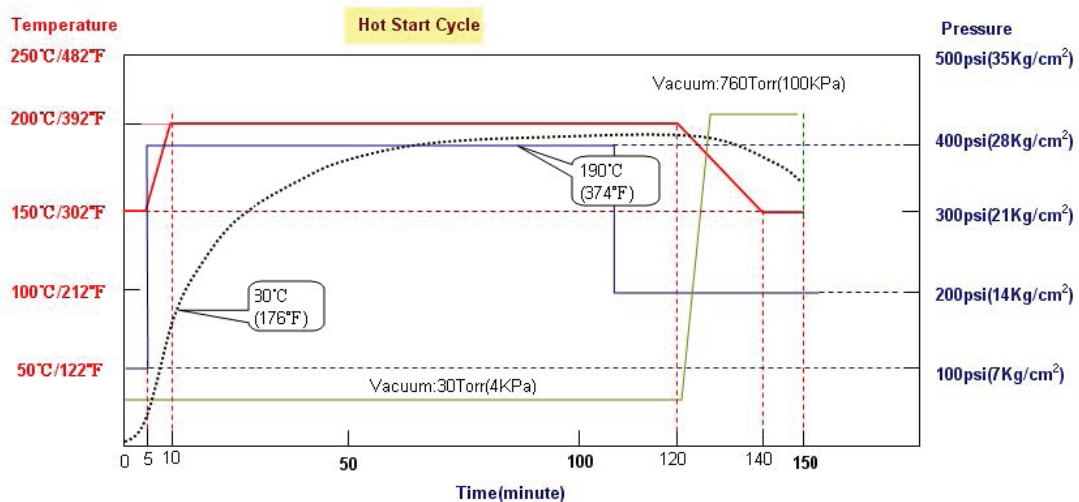
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Pressing Condition



1	Temp Ramp Rate	≥ 3.0 °C/min
2	Curing Time	≥ 185 °C / ~100min
3	Max. Material Temperature	200~205 °C
4	Full Pressure	≥28 kg (400 PSI)
5	Full Pressure Temperature	≤ 80 °C

Properties Sheet IPC-4101E /126

Properties		Test Method	Units	Specification
Tg	TMA	IPC-TM-650 2.4.24	°C	175
Td (5% Wt. Loss)		ASTM D3850	°C	360
Peel Strength (1oz)		IPC-TM-650 2.4.8	lb/in	6
T288		IPC-TM-650 2.4.24.1	Minute	>30
Z-axis CTE	Before Tg	IPC-TM-650 2.4.24	ppm/°C	50
	After Tg	IPC-TM-650 2.4.24	ppm/°C	220
	Total Expansion (50~260 °C)	IPC-TM-650 2.4.24	%	2.50
DK (RC 50%)	@ 10GHz	Cavity Resonator	-	3.8
DF (RC 50%)	@ 10GHz	Cavity Resonator	-	0.007

Disclaimer: The information and data contained in this technical literature is based on data and knowledge correct at the time of publishing/printing and is believed to be accurate and is offered in good faith for the benefit of the user. The user should make his own tests to verify the suitability of this product for any application before its use. All data are typical values only and subject to change without notice.

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